## **News Release**



January 26, 2024 JX Metals Corporation

## **Announcement of Organizational Changes**

JX Metals Corporation (President: Hayashi Yoichi; "the Company") will establish a CVD·ALD Material Business Promotion Office in the Advanced Technology & Strategy Department, Technology Group, effective February 1, 2024, aiming to achieve forward-looking business development in a new business area.

The market for materials used in the semiconductor devices-manufacturing process is expected to see continued growth. The Company's sputtering targets for semiconductors, which represent one of its core products, have secured the world's largest share of the market thanks to high appraisals across the industry for their effectiveness in the PVD¹ of thin films deposition on semiconductor chips. Because further miniaturization and multi-layering in cutting-edge semiconductors have progressed in the coming years, demand for thin film deposition - solutions via not only PVD but also the CVD and ALD² approaches will likely grow. The Company's new CVD·ALD Material Business Promotion Office will handle the entire scope of CVD and ALD materials for next-generation semiconductors, covering everything from efforts to identify development themes to mass-production in an integrated fashion, and work to accelerate the commercialization process.

- 1. PVD: Physical Vapor Deposition; the sputtering method is a common PVD process.
- 2. CVD: Chemical Vapor Deposition, which involves forming a thin film via a chemical reaction.
  - ALD: Atomic Layer Deposition, which involves controlling film thickness at the atomic level in forming a thin film.

